

ABSTRACT OF THE DISCLOSURE

A substrate such as a semiconductor wafer, a glass substrate, or a liquid crystal display is polished to a flat mirror finish, and then is cleaned to a high degree of cleanliness.

5 A polishing section having at least one polishing unit performs primary polishing and secondary polishing of the substrate by pressing the substrate against a polishing surface. A cleaning section cleans the substrate which has been polished to remove particles attached to the substrate by a scrubbing cleaning. Metal ions are removed from the substrate by supplying an etching liquid.

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